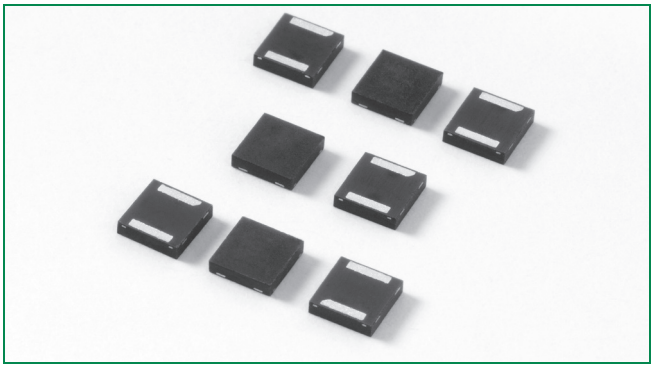
HF RoHS Fixed Voltage Q2L Series 3.3x3.3 QFN



Description

Fixed Voltage Q2L Series are uni-directional SIDACtor® devices designed to protect SLICs (Subscriber Line Interface Circuit) from damaging overvoltage transients.

The series provides single line protection using a fixed voltage switching device for negative surges. All positive surges are routed through an internal diode to a ground reference. The small size of the Q2L makes it ideal for high density applications.

Features and Benefits

- Integrated diode for positive voltage surges
- Low profile
- Small footprint QFN Package
- Low on-state voltage
- Does not degrade with use
- Fails short circuit when surged in excess of ratings

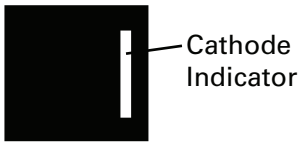
Agency Approvals

Agency	Agency File Number
	E133083

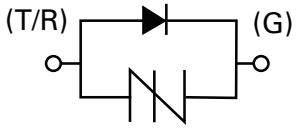
Applicable Global Standards

- GR-1089 Intra-building
- GR 1089 Inter-building
- ITU K.20/21/Basic
- ITU K.20/21/Enhanced
- TIA-968-A
- IEC 61000-4-5
- YD/T 950
- YD/T 993
- YD/T 1082

Pinout Designation



Schematic Symbol



Electrical Characteristics

Part Number	Marking	V_{DRM} @I_{DRM}=5µA	V_S @100V/µs	I_H	I_S	I_T	V_T @I_T=2.2 Amps	V_F	Capacitance @1MHz @ 2V bias	
		V min	V max	mA min	mA max	A max	V max	V max	pF min	pF max
P0641Q22CLRP	P61C	58	77	150	800	2.2	4	5	35	75
P0721Q22CLRP	P71C	65	88	150	800	2.2	4	5	25	45
P0901Q22CLRP	P91C	75	98	150	800	2.2	4	5	55	85
P1101Q22CLRP	P10C	95	130	150	800	2.2	4	5	50	75
P1301Q22CLRP	P13C	120	160	150	800	2.2	4	5	45	70
P1701Q22CLRP	P17C	160	200	150	800	2.2	4	5	45	70

Notes:
- Absolute maximum ratings measured at T_A= 25°C (unless otherwise noted).
- Devices are uni-directional

Surge Ratings

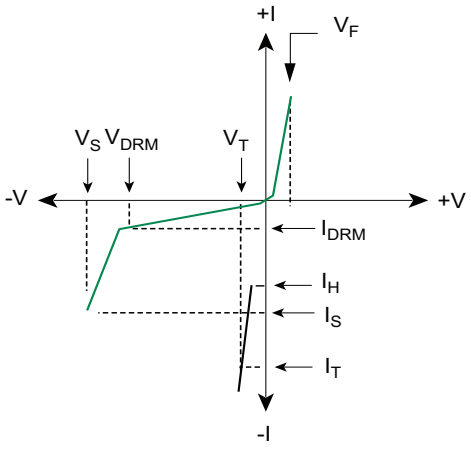
Series	I_{pp}					I_{TSM}	di/dt
	2x10µs	1.2x50µs/8x20µs	10x160µs	10x560µs	10x1000µs	50 / 60Hz	
	A min	A min	A min	A min	A min	A min	Amps/µs max
C	500	400	200	150	100	30	500

Notes:
- Peak pulse current rating (I_{PP}) is repetitive and guaranteed for the life of the product.
- I_{PP} ratings applicable over temperature range of -40°C to +85°C
- The device must initially be in thermal equilibrium with -40°C ≤ T_J ≤ +150°C

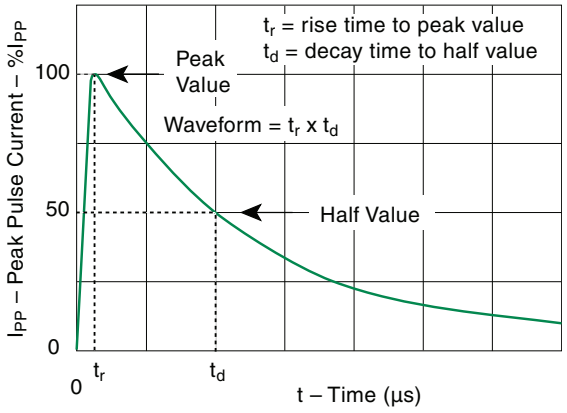
Thermal Considerations

Package	Symbol	Parameter	Value	Unit
3.3x3.3 QFN 	T_J	Operating Junction Temperature Range	-40 to +150	°C
	T_S	Storage Temperature Range	-65 to +150	°C
	$R_{\theta JA}$	Thermal Resistance: Junction to Ambient	120	°C/W

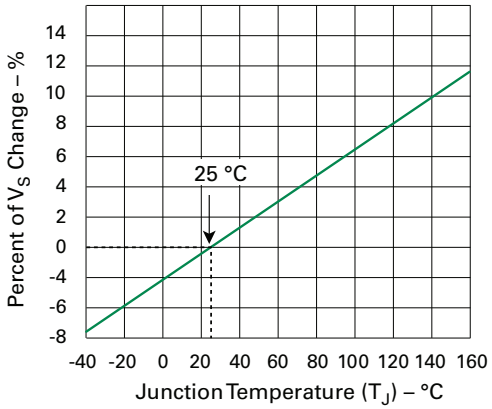
V-I Characteristics



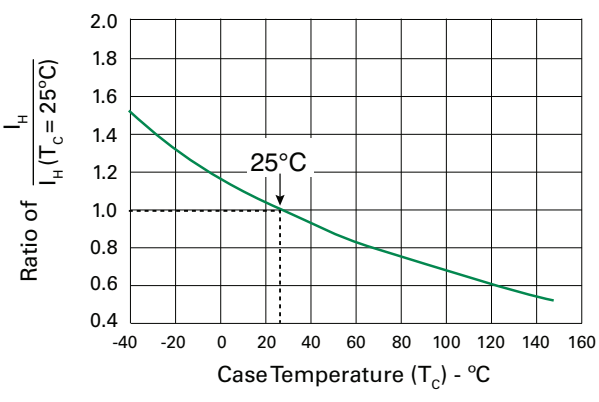
t_r x t_d Pulse Waveform



Normalized V_S Change vs. Junction Temperature



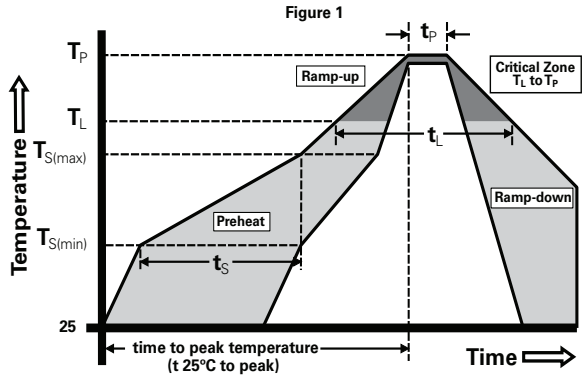
Normalized DC Holding Current vs. Case Temperature



Soldering Parameters

Reflow Condition		Pb-Free assembly (see Fig. 1)
Pre Heat	-Temperature Min ($T_{s(min)}$)	+150°C
	-Temperature Max ($T_{s(max)}$)	+200°C
	-Time (Min to Max) (t_s)	60-180 secs.
Average ramp up rate (Liquidus Temp (T_L) to peak)		3°C/sec. Max.
$T_{S(max)}$ to T_L - Ramp-up Rate		3°C/sec. Max.
Reflow	-Temperature (T_L) (Liquidus)	+217°C
	-Temperature (t_L)	60-150 secs.
Peak Temp (T_P)		+260(+0/-5)°C
Time within 5°C of actual Peak Temp (t_p)		30 secs. Max.
Ramp-down Rate		6°C/sec. Max.
Time 25°C to Peak Temp (T_P)		8 min. Max.
Do not exceed		+260°C

Figure 1



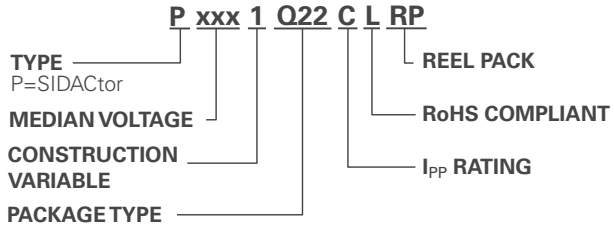
Physical Specifications

Lead Material	Copper Alloy
Terminal Finish	100% Matte-Tin Plated
Body Material	UL recognized epoxy meeting flammability classification 94V-0

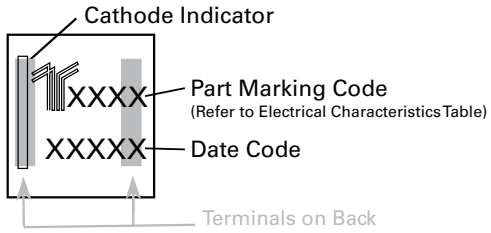
Environmental Specifications

High Temp Voltage Blocking	80% Rated V_{DRM} (V_{DC}) +125°C or +150°C, 504 or 1008 hrs. MIL-STD-750 (Method 1040) JEDEC, JESD22-A-101
Temp Cycling	-65°C to +150°C, 15 min. dwell, 10 up to 100 cycles. MIL-STD-750 (Method 1051) EIA/JEDEC, JESD22-A104
Biased Temp & Humidity	52 V_{DC} (+85°C) 85%RH, 504 up to 1008 hrs. EIA/JEDEC, JESD22-A-101
High Temp Storage	+150°C 1008 hrs. MIL-STD-750 (Method 1031) JEDEC, JESD22-A-101
Low Temp Storage	-65°C, 1008 hrs.
Thermal Shock	0°C to +100°C, 5 min. dwell, 10 sec. transfer, 10 cycles. MIL-STD-750 (Method 1056) JEDEC, JESD22-A-106
Resistance to Solder Heat	+260°C, 30 secs. MIL-STD-750 (Method 2031)
Moisture Sensitivity Level	85%RH, +85°C, 168 hrs., 3 reflow cycles (+260°C Peak). JEDEC-J-STD-020, Level 1

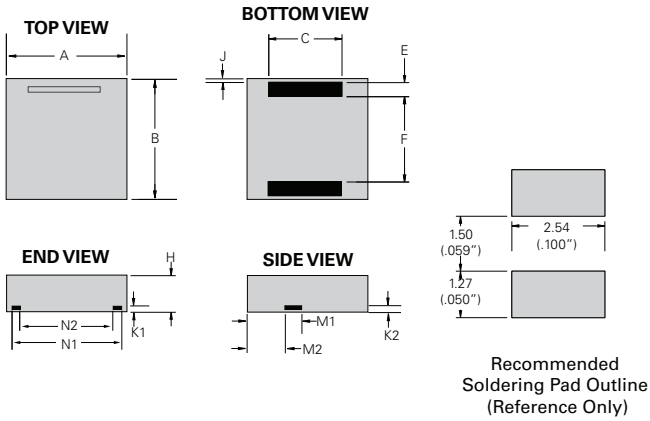
Part Numbering



Part Marking



Dimensions — 3.3x3.3 QFN



Recommended
Soldering Pad Outline
(Reference Only)

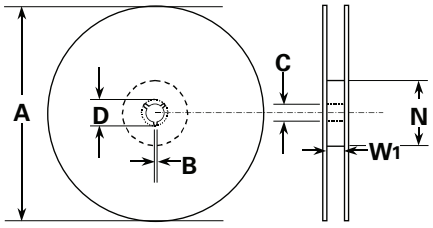
Dimensions	Inches		Millimeters	
	Min	Max	Min	Max
A	0.126	0.134	3.200	3.400
B	0.126	0.134	3.200	3.400
C	0.075	0.083	1.900	2.100
E	0.011	0.019	0.285	0.485
F	0.088	0.096	2.230	2.430
H	0.035	0.043	0.900	1.100
J	0.000	0.008	0.000	0.200
K1	0.004	0.012	0.100	0.300
K2	0.004	0.012	0.100	0.300
M1	0.063	0.071	1.610	1.810
M2	0.045	0.053	1.153	1.353
N1	0.095	0.103	2.420	2.620
N2	0.082	0.090	2.080	2.280

Packing Options

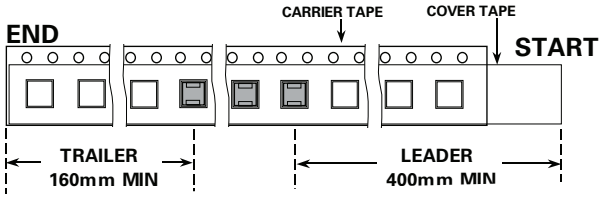
Package Type	Description	Quantity	Added Suffix	Industry Standard
Q22	3.3x3.3 QFN Tape and Reel Pack	5000	RP	EIA-481-D

Tape and Reel Dimension — 3.3x3.3 QFN

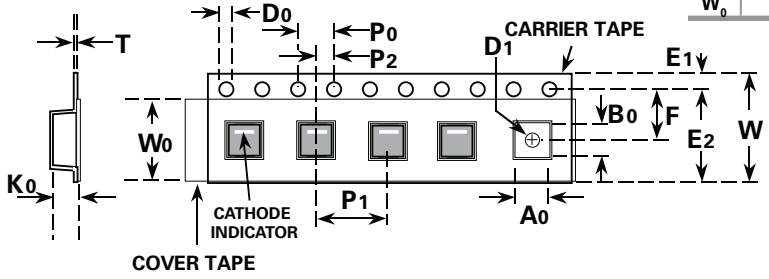
Reel Dimension



Tape Leader and Trailer Dimensions



Tape Dimension Items



	Description	Inches		Millimeters	
		Min	Max	Min	Max
A	Reel Diameter	N/A	12.992	N/A	330.0
B	Drive Spoke Width	0.059	N/A	1.50	N/A
C	Arbor Hole Diameter	0.504	0.531	12.80	13.50
D	Drive Spoke Diameter	0.795	N/A	20.20	N/A
N	Hub Diameter	1.969	N/A	50.00	N/A
W_1	Reel Inner Width at Hub	0.488	0.567	12.40	14.40
A_0	Pocket Width at bottom	0.138	0.146	3.50	3.70
B_0	Pocket Length at bottom	0.138	0.146	3.50	3.70
D_0	Feed Hole Diameter	0.059	0.063	1.50	1.60
D_1	Pocket Hole Diameter	0.059	N/A	1.50	N/A
E_1	Feed hole position 1	0.065	0.073	1.65	1.85
E_2	Feed hole position 2	0.400	0.408	10.15	10.35
F	Feed hole center-Pocket hole	0.215	0.219	5.45	5.55
K_0	Pocket Depth	0.039	0.051	1.00	1.30
P_0	Feed Hole Pitch	0.153	0.161	3.90	4.10
P_1	Component Spacing	0.311	0.319	7.90	8.10
P_2	Feed hole center-Pocket hole	0.077	0.081	1.95	2.05
T	Carrier Tape Thickness	0.010	0.014	0.25	0.35
W	Embossed Carrier Tape Width	0.453	0.484	11.50	12.30
W_0	Cover Tape Width	0.358	0.366	9.10	9.30